Preferred Device

SWITCHMODE™ Power Rectifier

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 50 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb-Free Devices*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in Plastic Bags; 1,000 per Bag
- Available Tape and Reel; 5,000 per Reel, by Adding a "RL" Suffix to the Part Number

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|--|--------------------------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 600 | ٧ |
| Average Rectified Forward Current (Note 1) (Square Wave Mounting Method #3 Per Note 3) | I _{F(AV)} | 2.0 @ T _A = 60°C | Α |
| Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz) | I _{FSM} | 35 | Α |
| Operating Junction Temperature and Storage Temperature Range | T _J , T _{stg} | -65 to +175 | °C |

THERMAL CHARACTERISTICS

| Characteristics | Symbol | Value | Unit |
|--|-----------------|---------------|------|
| Maximum Thermal Resistance, Junction–to–Ambient | $R_{\theta JA}$ | See Note 3 | °C/W |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

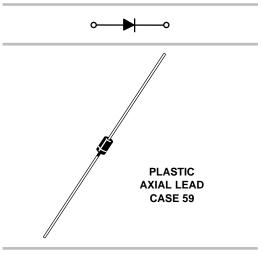
1. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER 2.0 AMPERES, 600 VOLTS



MARKING DIAGRAM



A = Assembly Location

/ = Year

WW = Work Week

= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-----------|--------------|-----------------------|
| MUR260 | Axial Lead** | 1000 Units/Bag |
| MUR260G | Axial Lead** | 1000 Units/Bag |
| MUR260RL | Axial Lead** | 5000/Tape & Reel |
| MUR260RLG | Axial Lead** | 5000/Tape & Reel |

- †For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
- **This package is inherently Pb-Free.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS

| Characteristics | Symbol | Value | Unit |
|---|-----------------|--------------|------|
| Maximum Instantaneous Forward Voltage (Note 2) ($I_F = 2.0 \text{ Amp}, T_J = 150^{\circ}\text{C}$) ($I_F = 2.0 \text{ Amp}, T_J = 25^{\circ}\text{C}$) | VF | 1.15 1.35 | V |
| Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 150^{\circ}$ C) (Rated dc Voltage, $T_J = 25^{\circ}$ C) | i _R | 150 5.0 | μΑ |
| Maximum Reverse Recovery Time ($I_F = 1.0$ Amp, di/dt = 50 Amp/ μ s) ($I_F = 0.5$ Amp, $I_R = 1.0$ Amp, $I_{REC} = 0.25$ A) | t _{rr} | 75 50 | ns |
| Maximum Forward Recovery Time (I _F = 1.0 A, di/dt = 100 A/μs, I _{REC} to 1.0 V) | t _{fr} | 50 | ns |

^{2.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

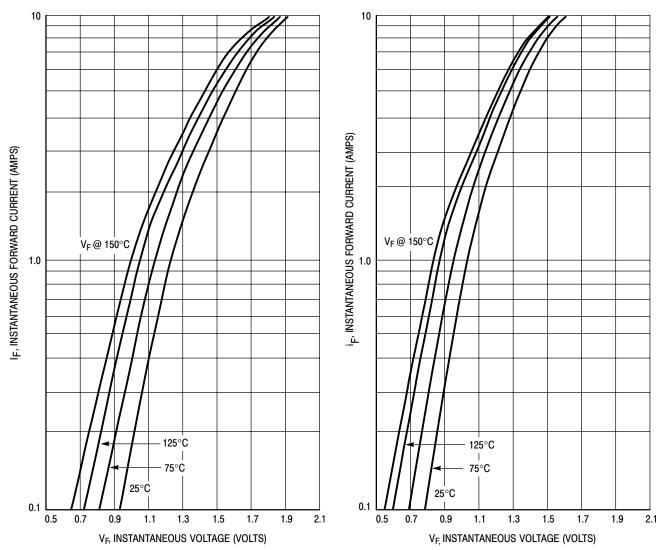


Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage

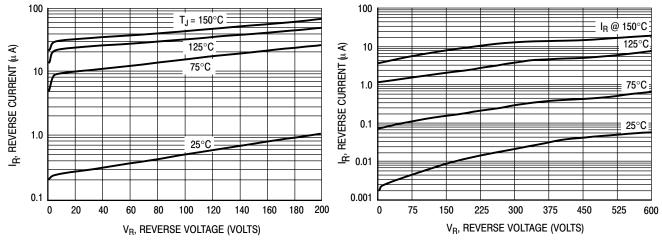


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current

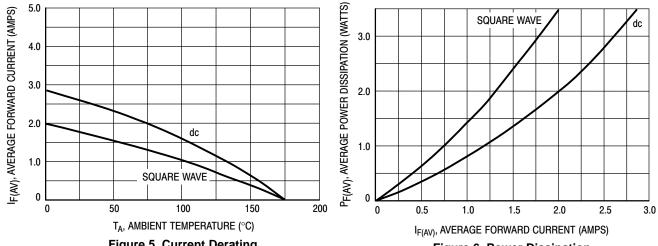


Figure 5. Current Derating

Figure 6. Power Dissipation

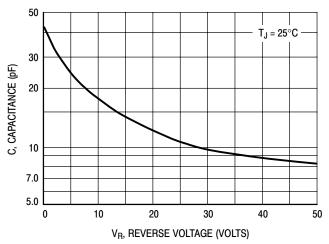


Figure 7. Typical Capacitance

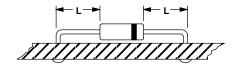
NOTE 3 — AMBIENT MOUNTING DATA

Data shown for thermal resistance, junction—to—ambient $(R_{\theta JA})$ for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

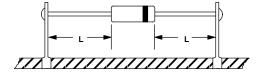
TYPICAL VALUES FOR $R_{\theta \text{JA}}$ IN STILL AIR

| Mounti | ng | Lead Length, L | | | |
|--------|-----------------|----------------|-----|-----|-------|
| Metho | d | 1/8 | 1/4 | 1/2 | Units |
| 1 | | 52 | 65 | 72 | °C/W |
| 2 | $R_{\theta JA}$ | 67 | 80 | 87 | °C/W |
| 3 | | | 50 | | °C/W |

MOUNTING METHOD 1

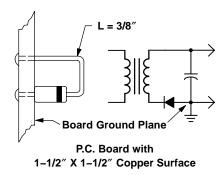


MOUNTING METHOD 2



Vector Pin Mounting

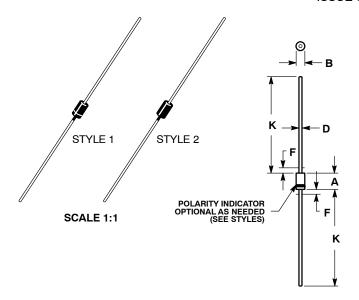
MOUNTING METHOD 3



SWITCHMODE is a trademark of Semiconductor Components Industries, LLC.

AXIAL LEAD CASE 59-10 **ISSUE U**

DATE 15 FEB 2005



STYLE 1: PIN 1. CATHODE (POLARITY BAND) STYLE 2: NO POLARITY

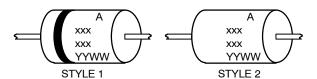
2. ANODE

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

- CONTROLLING DIMENSION: INCH. ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY POLARITY DENOTED BY CATHODE BAND. LEAD DIAMETER NOT CONTROLLED WITHIN F DIMENSION.

| | INCHES | | MILLIM | ETERS |
|-----|--------|-------|--------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.161 | 0.205 | 4.10 | 5.20 |
| В | 0.079 | 0.106 | 2.00 | 2.70 |
| D | 0.028 | 0.034 | 0.71 | 0.86 |
| F | | 0.050 | | 1.27 |
| K | 1.000 | | 25.40 | |

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Assembly Location Α

YY = Year WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

| DOCUMENT NUMBER: | 98ASB42045B | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. | | |
|------------------|-------------|---|-------------|--|
| DESCRIPTION: | AXIAL LEAD | | PAGE 1 OF 1 | |

ON Semiconductor and at a trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Rectifiers category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

70HFR40 RL252-TP 150KR30A 1N5397 NTE5841 NTE6038 SCF5000 1N4002G 1N4005-TR JANS1N6640US 481235F
RRE02VS6SGTR 067907F MS306 70HF40 T85HFL60S02 US2JFL-TP A1N5404G-G CRS04(T5L,TEMQ) ACGRA4007-HF
ACGRB207-HF CLH03(TE16L,Q) ACGRC307-HF ACEFC304-HF NTE6356 NTE6359 NTE6002 NTE6023 NTE6039 NTE6077
85HFR60 40HFR60 70HF120 85HFR80 D126A45C SCF7500 D251N08B SCHJ22.5K SM100 SCPA2 SCH10000 SDHD5K VS12FL100S10 ACGRA4001-HF D1821SH45T PR D1251S45T NTE5990 NTE6358 NTE6162 NTE5850